



	LAA710	Units
Load Voltage	60	V
Load Current	1.0	A
Max R _{ON}	0.5	Ω

Features

- Small 8 Pin DIP Package
- Low Drive Power Requirements (TTL/CMOS Compatible)
- No Moving Parts
- High Reliability
- Arc-Free With No Snubbing Circuits
- 3750V_{RMS} Input/Output Isolation
- No EMI/RFI Generation
- Machine Insertable, Wave Solderable
- Surface Mount and Tape & Reel Versions Available

Applications

- Telecommunications
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
 - Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

LAA710 is a Dual 1 Form-A solid state relay that has two independently controlled optically coupled MOSFETs. The efficient MOSFET switches and photovoltaic die use Clare's patented OptoMOS® architecture to provide 3750 V_{RMS} of input to output isolation. The optically coupled inputs are controlled by highly efficient GaAlAs infrared LEDs. Dual pole OptoMOS relays provide a more compact design solution than discrete single pole relays in a variety of applications. The dual pole relays save board space by incorporating both relays in a single 8-pin package.

Approvals

- UL Recognized: File Number E76270
- CSA Certified: File Number LR 43639-10
- BSI Certified:
 - BS EN 60950:1992 (BS7002:1992) Certificate #:7344
 - BS EN 41003:1993 Certificate #:7344

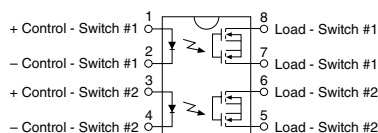
Ordering Information

Part #	Description
LAA710	8 Pin DIP (50/Tube)
LAA710S	8 Pin Surface Mount (50/Tube)
LAA710STR	8 Pin Surface Mount (1000/Reel)

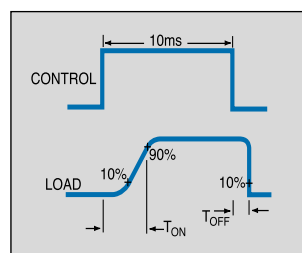
Pin Configuration

LAA710 Pinout

AC/DC Configuration



Switching Characteristics of Normally Open (Form A) Devices



Absolute Maximum Ratings (@ 25° C)

Parameter	Min	Typ	Max	Units
Input Power Dissipation	-	-	150 ¹	mW
Input Control Current	-	-	50	mA
Peak (10ms)	-	-	1	A
Reverse Input Voltage	-	-	5	V
Blocking Voltage	-	-	60	V
Total Power Dissipation	-	-	800 ²	mW
Isolation Voltage Input to Output	-	-	3750	V _{RMS}
Operational Temperature	-40	-	+85	°C
Storage Temperature	-40	-	+125	°C
Soldering Temperature DIP Package	-	-	+260	°C
Flatpack/Surface Mount Package (10 Seconds Max.)	-	-	+220	°C

¹ Derate Linearly 1.33 mW/°C

² Derate Linearly 6.67 mW/°C

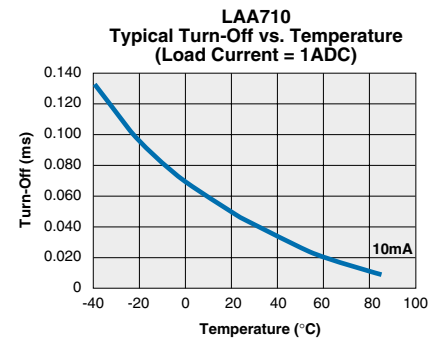
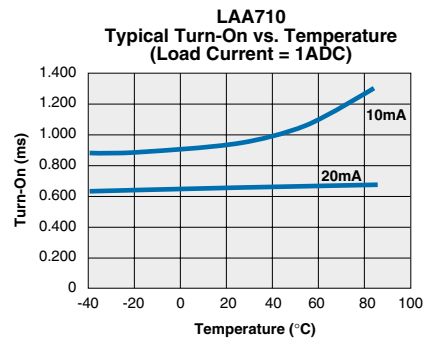
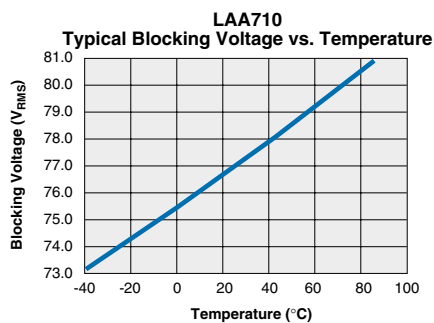
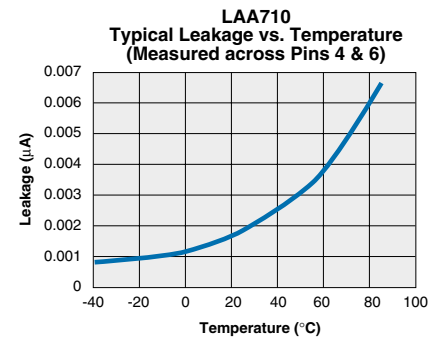
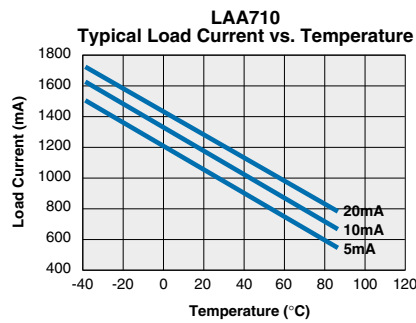
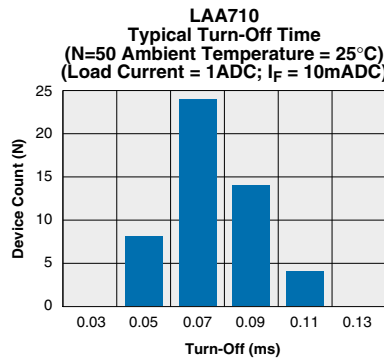
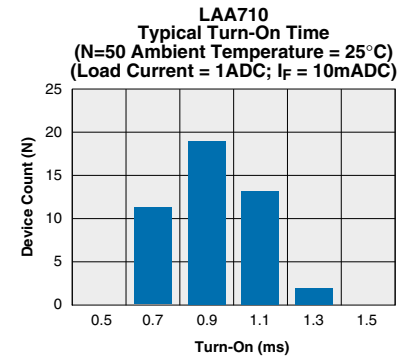
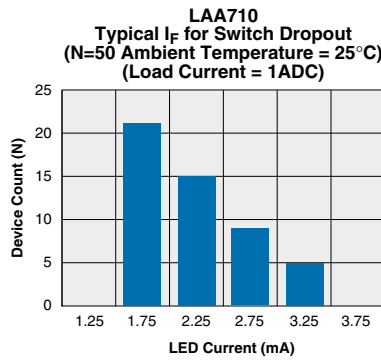
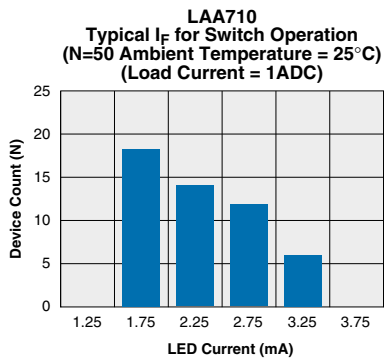
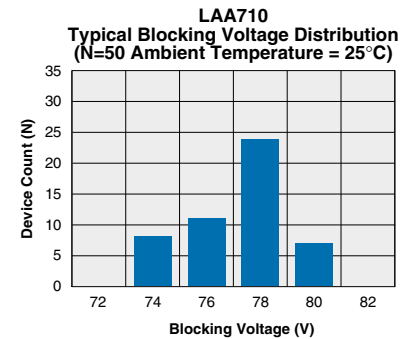
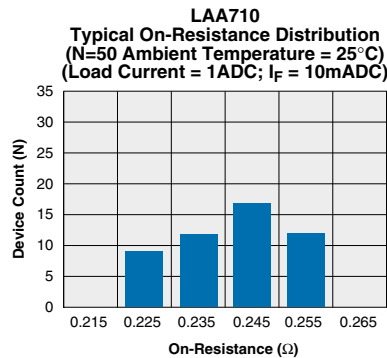
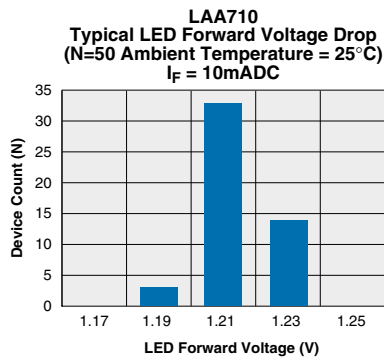
Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Electrical Characteristics

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics @ 25°C						
Load Current* (Continuous) AC/DC Configuration	-	I _L	-	-	1.0	A
Peak Load Current	10ms	I _{LPK}	-	-	5.0	A
On-Resistance AC/DC Configuration	I _L =1.0A	R _{ON}	-	-	0.5	Ω
Off-State Leakage Current	V _L =60V	I _{LEAK}	-	-	1	μA
Switching Speeds Turn-On	I _F =5mA, V _L =10V	T _{ON}	-	-	2.5	ms
Turn-Off	I _F =5mA, V _L =10V	T _{OFF}	-	-	0.25	ms
Output Capacitance	50V; f=1MHz	C _{OUT}	-	220	-	pF
Input Characteristics @ 25°C						
Input Control Current	I _L =150mA	I _F	10	-	50	mA
Input Dropout Current	-	I _F	0.4	0.7	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Voltage	-	V _R	-	-	5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Input to Output Capacitance	-	C _{I/O}	-	3	-	pF

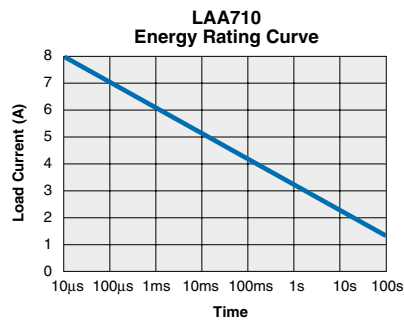
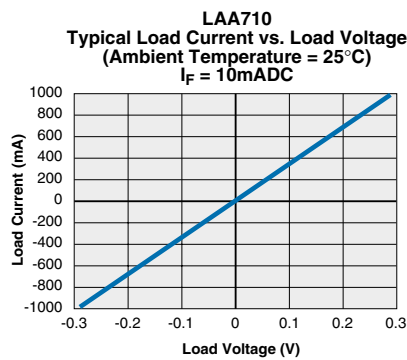
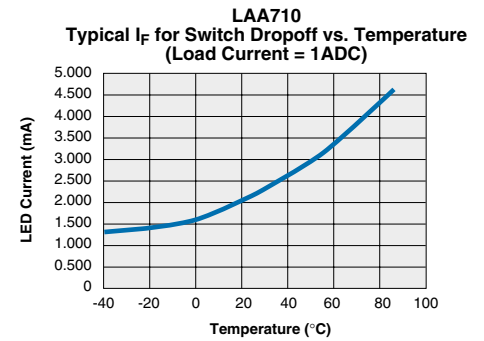
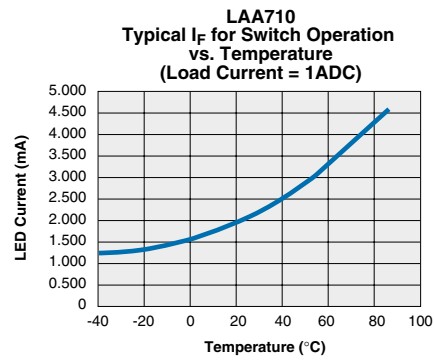
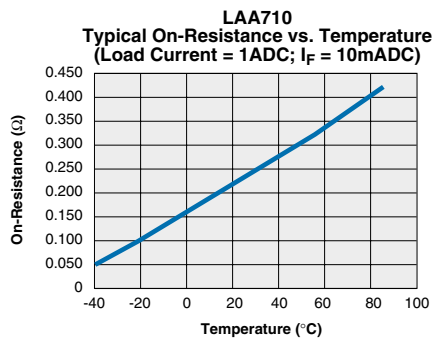
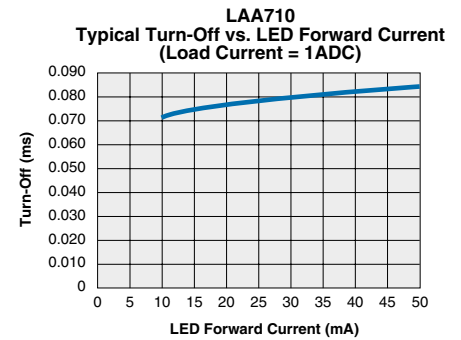
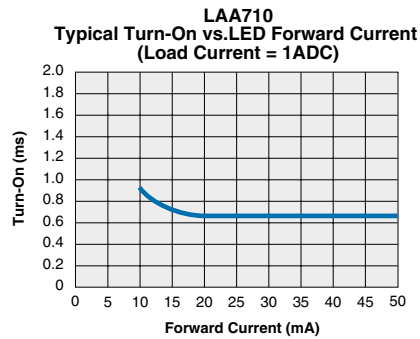
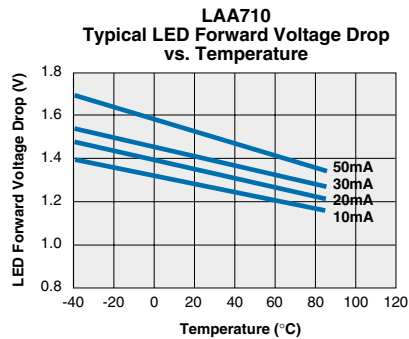
*NOTE: If both poles operate simultaneously load current must be derated so as not to exceed the package power dissipation value.

PERFORMANCE DATA*



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

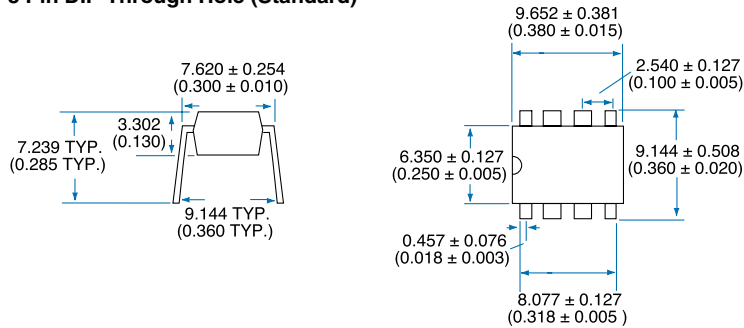
PERFORMANCE DATA*



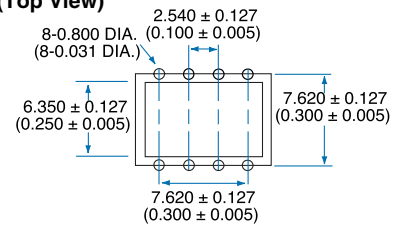
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MECHANICAL DIMENSIONS

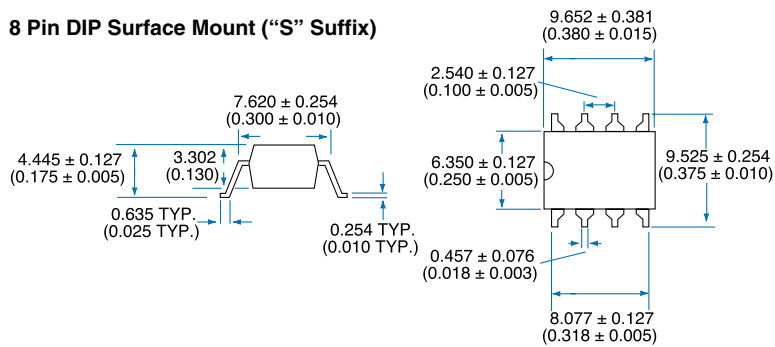
8 Pin DIP Through Hole (Standard)



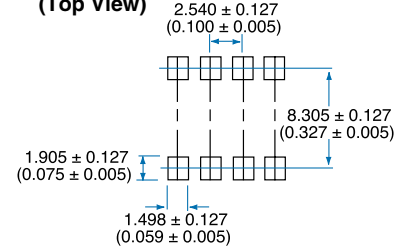
PC Board Pattern (Top View)



8 Pin DIP Surface Mount ("S" Suffix)



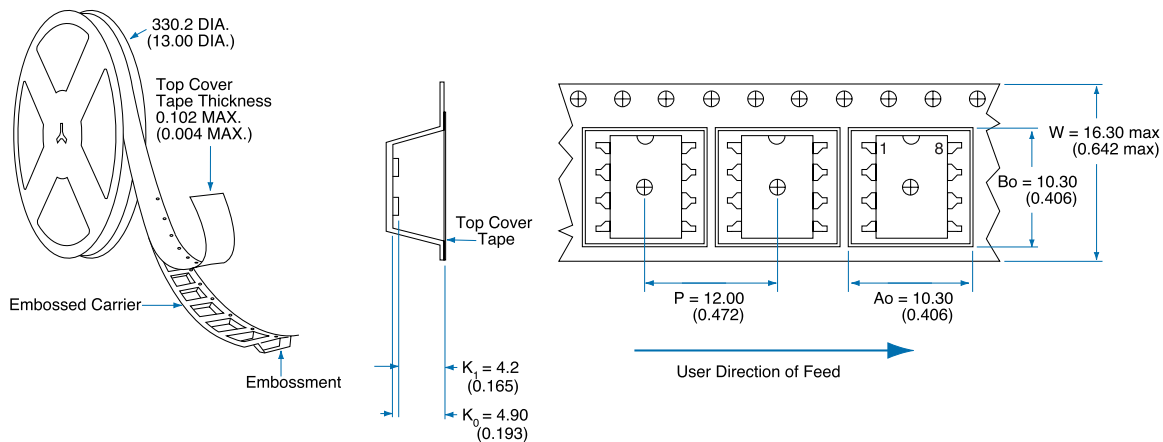
PC Board Pattern (Top View)



Dimensions
mm
(inches)

MECHANICAL DIMENSIONS

Tape and Reel Packaging for 8 Pin Surface Mount Package



NOTE: Tape dimensions not shown, comply with JEDEC Standard EIA-481-2

Dimensions
mm
(inches)

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